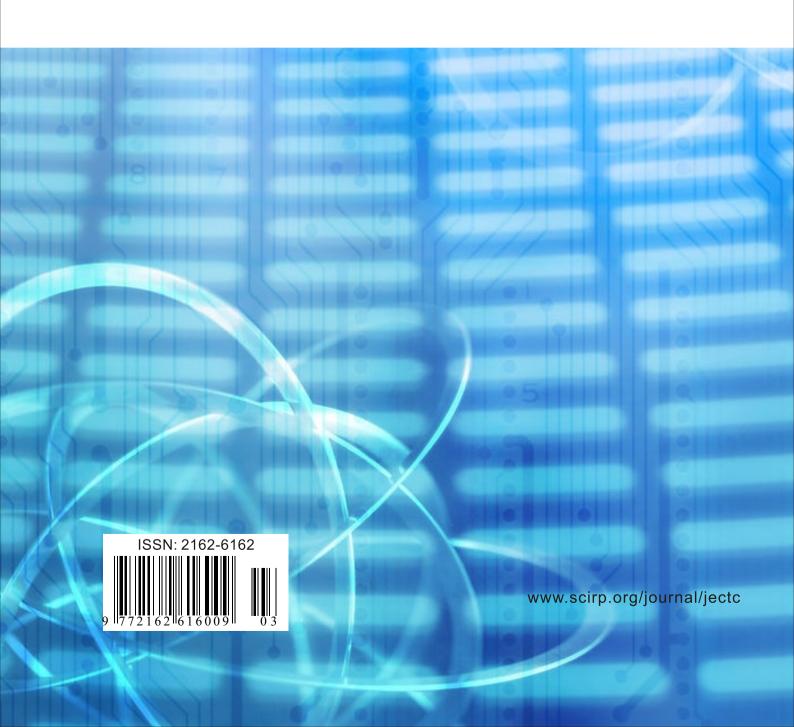


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TABLE OF CONTENTS

Volume 1	Number 3	December 2011
Effect of Hear	Extraction by Metal Lines and Two Sided Cooling on Temperatures in	
Organic Ligh	t Emitting	
Deepak, G. N	I. Shukla	29
Experimental	Study of Jet Nanofluids Impingement System for Cooling Computer Pro	ocessing Unit
P. Naphon, S	. Wongwises	38

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Journal of Electronics Cooling and Thermal Control (JECTC) is a quarterly, peer-reviewed, academic journal. It aims to provide a vehicle for the exchange and dissemination of original research results, technical notes, and state-of-the-art reviews pertaining to the electronic cooling and thermal system control technology in the computer and electronics industries.

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This journal invites original research and review papers that address the following issues. Topics of interest include, but are not limited to:

Fundamentals and applications of heat/mass transfer processes for the electronics and micro-electronics, such as

- Base board design and material structure
- Control scenario
- Fan design and performance
- Forced convection heat transfer
- Heat storage
- High heat conductive materials
- Insulation
- Interface thermal contact performance
- Natural convection heat transfer
- Phase changing heat transfer
- Phonon
- Radiation
- Spray cooling
- Temperature stability

Technologies based on these transport processes such as

- Enhanced heat/mass transfer in precision-, micro-electronics, information technology
- Heat pipe
- MEMS (Micro-Electro-Mechanical-Systems) and NEMS (Nano-Electro-Mechanical-Systems)
- Various electronic devices, etc.

We are also interested in: 1) Short reports—2-5 page papers where an author can either present an idea with theoretical background but has not yet completed the research needed for a complete paper or preliminary data; 2) Book reviews—Comments and critiques.

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